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Details

Product Status	Active
Number of LABs/CLBs	-
Number of Logic Elements/Cells	-
Total RAM Bits	516096
Number of I/O	620
Number of Gates	3000000
Voltage - Supply	1.425V ~ 1.575V
Mounting Type	Surface Mount
Operating Temperature	-55°C ~ 125°C (TJ)
Package / Case	896-BGA
Supplier Device Package	896-FBGA (31x31)
Purchase URL	https://www.e-xfl.com/product-detail/microchip-technology/a3pe3000l-fg896m

**Table 2-28 • Summary of Maximum and Minimum DC Input Levels
Applicable to Military Conditions**

DC I/O Standard	Military ¹	
	I_{IL} ²	I_{IH} ³
	μA	μA
3.3 V LVTTTL / 3.3 V LVCMOS	15	15
3.3 V LVCMOS Wide Range	15	15
2.5 V LVCMOS	15	15
1.8 V LVCMOS	15	15
1.5 V LVCMOS	15	15
1.2 V LVCMOS ⁴	15	15
1.2 V LVCMOS Wide Range ⁴	15	15
3.3 V PCI	15	15
3.3 V PCI-X	15	15
3.3 V GTL	15	15
2.5 V GTL	15	15
3.3 V GTL+	15	15
2.5 V GTL+	15	15
HSTL (I)	15	15
HSTL (II)	15	15
SSTL2 (I)	15	15
SSTL2 (II)	15	15
SSTL3 (I)	15	15
SSTL3 (II)	15	15

Notes:

1. Military temperature range: $-55^{\circ}C$ to $125^{\circ}C$.
2. I_{IL} is the input leakage current per I/O pin over recommended operation conditions where $-0.3 V < V_{IN} < V_{IL}$.
3. I_{IH} is the input leakage current per I/O pin over recommended operating conditions $V_{IH} < V_{IN} < V_{CCI}$. Input current is larger when operating outside recommended ranges.
4. Applicable to Military A3PE600L and A3PE3000L devices operating at $V_{CCI} \geq V_{CC}$.

Table 2-38 • I/O Output Buffer Maximum Resistances¹
Applicable to Standard Plus I/O Banks for A3P250 and A3P1000 Only

Standard	Drive Strength	R _{PULL-DOWN} (Ω) ²	R _{PULL-UP} (Ω) ³
3.3 V LVTTTL / 3.3 V LVCMOS	2 mA	100	300
	4 mA	100	300
	6 mA	50	150
	8 mA	50	150
	12 mA	25	75
	16 mA	25	75
3.3 V LVCMOS Wide Range	100 μA	Same as regular 3.3 V LVCMOS	
2.5 V LVCMOS	2 mA	100	200
	4 mA	100	200
	6 mA	50	100
	8 mA	50	100
	12 mA	25	50
1.8 V LVCMOS	2 mA	200	225
	4 mA	100	112
	6 mA	50	56
	8 mA	50	56
1.5 V LVCMOS	2 mA	200	224
	4 mA	100	112
3.3 V PCI/PCI-X	Per PCI/PCI-X specification	25	75

Notes:

1. These maximum values are provided for informational reasons only. Minimum output buffer resistance values depend on V_{CCI}, drive strength selection, temperature, and process. For board design considerations and detailed output buffer resistances, use the corresponding IBIS models located at <http://www.microsemi.com/products/fpga-soc/design-resources/ibis-models>.
2. $R_{(PULL-DOWN-MAX)} = (VOL_{spec}) / IOL_{spec}$
3. $R_{(PULL-UP-MAX)} = (VCCImax - VOH_{spec}) / IOH_{spec}$

Table 2-39 • I/O Weak Pull-Up/Pull-Down Resistances
Minimum and Maximum Weak Pull-Up/Pull-Down Resistance Values

VCCI	R _(WEAK PULL-UP) ¹ (Ω)		R _(WEAK PULL-DOWN) ² (Ω)	
	Min.	Max.	Min.	Max.
3.3 V	10 k	95 k	13 k	45 k
3.3 V (wide range I/Os)	10 k	95 k	13 k	45 k
2.5 V	11 k	100 k	17 k	74 k
1.8 V	19 k	85 k	23 k	110 k
1.5 V	20 k	120 k	17 k	156 k
1.2 V	30 k	450 k	25 k	300 k
1.2 V (wide range I/Os)	20 k	450 k	17 k	300 k

Notes:

1. $R_{(WEAK PULL-UP-MAX)} = (VCCImax - VOH_{spec}) / I_{(WEAK PULL-UP-MIN)}$
2. $R_{(WEAK PULL-DOWN-MAX)} = (VOL_{spec}) / I_{(WEAK PULL-UP-MIN)}$

2.5 V LVCMOS

Low-Voltage CMOS for 2.5 V is an extension of the LVCMOS standard (JESD8-5) used for general-purpose 2.5 V applications.

Table 2-70 • Minimum and Maximum DC Input and Output Levels
Applicable to Pro I/Os for A3PE600L and A3PE3000L Only

2.5 V LVCMOS	VIL		VIH		VOL	VOH	IOL	IOH	IOSL	IOSH	IIL ¹	IIH ²
Drive Strength	Min. V	Max. V	Min. V	Max. V	Max. V	Min. V	mA	mA	Max. mA ³	Max. mA ³	μA ⁴	μA ⁴
4 mA	−0.3	0.7	1.7	3.6	0.7	1.7	4	4	16	18	15	15
8 mA	−0.3	0.7	1.7	3.6	0.7	1.7	8	8	32	37	15	15
12 mA	−0.3	0.7	1.7	3.6	0.7	1.7	12	12	65	74	15	15
16 mA	−0.3	0.7	1.7	3.6	0.7	1.7	16	16	83	87	15	15
24 mA	−0.3	0.7	1.7	3.6	0.7	1.7	24	24	169	124	15	15

Notes:

1. I_{IL} is the input leakage current per I/O pin over recommended operation conditions where $-0.3\text{ V} < V_{IN} < V_{IL}$.
2. I_{IH} is the input leakage current per I/O pin over recommended operating conditions $V_{IH} < V_{IN} < V_{CCI}$. Input current is larger when operating outside recommended ranges
3. Currents are measured at 100°C junction temperature and maximum voltage.
4. Currents are measured at 125°C junction temperature.
5. Software default selection highlighted in gray.

Table 2-71 • Minimum and Maximum DC Input and Output Levels
Applicable to Advanced I/O Banks

2.5 V LVCMOS	VIL		VIH		VOL	VOH	IOL	IOH	IOSL	IOSH	IIL ¹	IIH ²
Drive Strength	Min. V	Max. V	Min. V	Max. V	Max. V	Min. V	mA	mA	Max. mA ³	Max. mA ³	μA ⁴	μA ⁴
2 mA	−0.3	0.7	1.7	2.7	0.7	1.7	2	2	16	18	15	15
4 mA	−0.3	0.7	1.7	2.7	0.7	1.7	4	4	16	18	15	15
6 mA	−0.3	0.7	1.7	2.7	0.7	1.7	6	6	32	37	15	15
8 mA	−0.3	0.7	1.7	2.7	0.7	1.7	8	8	32	37	15	15
12 mA	−0.3	0.7	1.7	2.7	0.7	1.7	12	12	65	74	15	15
16 mA	−0.3	0.7	1.7	2.7	0.7	1.7	16	16	83	87	15	15
24 mA	−0.3	0.7	1.7	2.7	0.7	1.7	24	24	169	124	15	15

Notes:

1. I_{IL} is the input leakage current per I/O pin over recommended operation conditions where $-0.3\text{ V} < V_{IN} < V_{IL}$.
2. I_{IH} is the input leakage current per I/O pin over recommended operating conditions $V_{IH} < V_{IN} < V_{CCI}$. Input current is larger when operating outside recommended ranges
3. Currents are measured at 100°C junction temperature and maximum voltage.
4. Currents are measured at 125°C junction temperature.
5. Software default selection highlighted in gray.

1.8 V LVCMOS

Low-voltage CMOS for 1.8 V is an extension of the LVCMOS standard (JESD8-5) used for general-purpose 1.8 V applications. It uses a 1.8 V input buffer and a push-pull output buffer.

Table 2-82 • Minimum and Maximum DC Input and Output Levels
Applicable to Pro I/Os for A3PE600L and A3PE3000L Only

1.8 V LVCMOS	VIL		VIH		VOL	VOH	IOL	IOH	IOSL	IOSH	IIL ¹	IIH ²
Drive Strength	Min. V	Max. V	Min. V	Max. V	Max. V	Min. V	mA	mA	Max. mA ³	Max. mA ³	μA ⁴	μA ⁴
2 mA	−0.3	0.35 * VCCI	0.65 * VCCI	3.6	0.45	VCCI − 0.45	2	2	9	11	15	15
4 mA	−0.3	0.35 * VCCI	0.65 * VCCI	3.6	0.45	VCCI − 0.45	4	4	17	22	15	15
6 mA	−0.3	0.35 * VCCI	0.65 * VCCI	3.6	0.45	VCCI − 0.45	6	6	35	44	15	15
8 mA	−0.3	0.35 * VCCI	0.65 * VCCI	3.6	0.45	VCCI − 0.45	8	8	45	51	15	15
12 mA	−0.3	0.35 * VCCI	0.65 * VCCI	3.6	0.45	VCCI − 0.45	12	12	91	74	15	15
16 mA	−0.3	0.35 * VCCI	0.65 * VCCI	3.6	0.45	VCCI − 0.45	16	16	91	74	15	15

Notes:

1. I_{IL} is the input leakage current per I/O pin over recommended operation conditions where $-0.3\text{ V} < V_{IN} < V_{IL}$.
2. I_{IH} is the input leakage current per I/O pin over recommended operating conditions $V_{IH} < V_{IN} < V_{CCI}$. Input current is larger when operating outside recommended ranges
3. Currents are measured at 100°C junction temperature and maximum voltage.
4. Currents are measured at 125°C junction temperature.
5. Software default selection highlighted in gray.

Table 2-83 • Minimum and Maximum DC Input and Output Levels
Applicable to Advanced I/O Banks

1.8 V LVCMOS	VIL		VIH		VOL	VOH	IOL	IOH	IOSL	IOSH	IIL ¹	IIH ²
Drive Strength	Min. V	Max. V	Min. V	Max. V	Max. V	Min. V	mA	mA	Max. mA ³	Max. mA ³	μA ⁴	μA ⁴
2 mA	−0.3	0.35 * VCCI	0.65 * VCCI	1.9	0.45	VCCI − 0.45	2	2	9	11	15	15
4 mA	−0.3	0.35 * VCCI	0.65 * VCCI	1.9	0.45	VCCI − 0.45	4	4	17	22	15	15
6 mA	−0.3	0.35 * VCCI	0.65 * VCCI	1.9	0.45	VCCI − 0.45	6	6	35	44	15	15
8 mA	−0.3	0.35 * VCCI	0.65 * VCCI	1.9	0.45	VCCI − 0.45	8	8	45	51	15	15
12 mA	−0.3	0.35 * VCCI	0.65 * VCCI	1.9	0.45	VCCI − 0.45	12	12	91	74	15	15
16 mA	−0.3	0.35 * VCCI	0.65 * VCCI	1.9	0.45	VCCI − 0.45	16	16	91	74	15	15

Notes:

1. I_{IL} is the input leakage current per I/O pin over recommended operation conditions where $-0.3\text{ V} < V_{IN} < V_{IL}$.
2. I_{IH} is the input leakage current per I/O pin over recommended operating conditions $V_{IH} < V_{IN} < V_{CCI}$. Input current is larger when operating outside recommended ranges
3. Currents are measured at 100°C junction temperature and maximum voltage.
4. Currents are measured at 125°C junction temperature.
5. Software default selection highlighted in gray.

1.5 V DC Core Voltage

Table 2-100 • 1.5 V LVCMOS Low Slew

Military-Case Conditions: $T_J = 125^{\circ}\text{C}$, $V_{CC} = 1.425\text{ V}$, Worst-Case $V_{CCI} = 1.4\text{ V}$
Applicable to Pro I/Os for A3PE600L and A3PE3000L Only

Drive Strength	Speed Grade	t_{DOUT}	t_{DP}	t_{DIN}	t_{PY}	t_{PYS}	t_{EOUT}	t_{ZL}	t_{ZH}	t_{LZ}	t_{HZ}	t_{ZLS}	t_{ZHS}	Units
2 mA	Std.	0.61	9.39	0.04	1.88	2.77	0.40	9.54	7.77	3.22	2.47	11.00	9.24	ns
	–1	0.52	7.99	0.03	1.60	2.35	0.34	8.11	6.61	2.74	2.10	9.36	7.86	ns
4 mA	Std.	0.61	8.01	0.04	1.88	2.77	0.40	8.13	6.77	3.58	3.14	9.59	8.24	ns
	–1	0.52	6.81	0.03	1.60	2.35	0.34	6.91	5.76	3.05	2.67	8.16	7.01	ns
6 mA	Std.	0.61	7.51	0.04	1.88	2.77	0.40	7.62	6.59	3.66	3.32	9.09	8.05	ns
	–1	0.52	6.39	0.03	1.60	2.35	0.34	6.48	5.60	3.12	2.83	7.73	6.85	ns
8 mA	Std.	0.61	7.41	0.04	1.88	2.77	0.40	7.52	6.59	3.41	3.99	8.99	8.06	ns
	–1	0.52	6.30	0.03	1.60	2.35	0.34	6.40	5.61	2.90	3.40	7.64	6.85	ns
12 mA	Std.	0.61	7.41	0.04	1.88	2.77	0.40	7.52	6.59	3.41	3.99	8.99	8.06	ns
	–1	0.52	6.30	0.03	1.60	2.35	0.34	6.40	5.61	2.90	3.40	7.64	6.85	ns

Note: For specific junction temperature and voltage supply levels, refer to [Table 2-6 on page 2-6](#) for derating values.

Table 2-101 • 1.5 V LVCMOS High Slew

Military-Case Conditions: $T_J = 125^{\circ}\text{C}$, $V_{CC} = 1.425\text{ V}$, Worst-Case $V_{CCI} = 1.4\text{ V}$
Applicable to Pro I/Os for A3PE600L and A3PE3000L Only

Drive Strength	Speed Grade	t_{DOUT}	t_{DP}	t_{DIN}	t_{PY}	t_{PYS}	t_{EOUT}	t_{ZL}	t_{ZH}	t_{LZ}	t_{HZ}	t_{ZLS}	t_{ZHS}	Units
2 mA	Std.	0.61	3.78	0.04	1.88	2.77	0.40	3.82	3.43	3.21 ¹	2.58	5.29	4.89	ns
	–1	0.52	3.21	0.03	1.60	2.35	0.34	3.25	2.92	2.73	2.20	4.50	4.16	ns
4 mA	Std.	0.61	3.20	0.04	1.88	2.77	0.40	3.23	2.79	3.57	3.25	4.70	4.25	ns
	–1	0.52	2.72	0.03	1.60	2.35	0.34	2.75	2.37	3.04	2.77	4.00	3.62	ns
6 mA	Std.	0.61	3.09	0.04	1.88	2.77	0.40	3.12	2.67	3.65	3.44	4.59	4.13	ns
	–1	0.52	2.63	0.03	1.60	2.35	0.34	2.65	2.27	3.11	2.93	3.90	3.52	ns
8 mA	Std.	0.61	3.05	0.04	1.88	2.77	0.40	3.09	2.52	3.77	4.14	4.55	3.98	ns
	–1	0.52	2.60	0.03	1.60	2.35	0.34	2.62	2.14	3.21	3.52	3.87	3.39	ns
12 mA	Std.	0.61	3.05	0.04	1.88	2.77	0.40	3.09	2.52	3.77	4.14	4.55	3.98	ns
	–1	0.52	2.60	0.03	1.60	2.35	0.34	2.62	2.14	3.21	3.52	3.87	3.39	ns

Notes:

- Software default selection highlighted in gray.
- For specific junction temperature and voltage supply levels, refer to [Table 2-6 on page 2-6](#) for derating values.

2.5 V GTL

Gunning Transceiver Logic is a high-speed bus standard (JESD8-3). It provides a differential amplifier input buffer and an open-drain output buffer. The V_{CCI} pin should be connected to 2.5 V.

Table 2-124 • Minimum and Maximum DC Input and Output Levels

2.5 V GTL	VIL		VIH		VOL	VOH	IOL	IOH	IOSL	IOSH	IIL ¹	IIH ²
Drive Strength	Min. V	Max. V	Min. V	Max. V	Max. V	Min. V	mA	mA	Max. mA ³	Max. mA ³	μA ⁴	μA ⁴
20 mA ⁵	-0.3	VREF - 0.05	VREF + 0.05	3.6	0.4	-	20	20	169	124	15	15

Notes:

1. I_{IL} is the input leakage current per I/O pin over recommended operating conditions where $-0.3 \text{ V} < V_{IN} < V_{IL}$.
2. I_{IH} is the input leakage current per I/O pin over recommended operating conditions $V_{IH} < V_{IN} < V_{CCI}$. Input current is larger when operating outside recommended ranges.
3. Currents are measured at 100°C junction temperature and maximum voltage.
4. Currents are measured at 125°C junction temperature.
5. Output drive strength is below JEDEC specification.

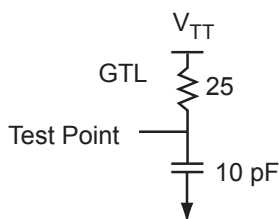


Figure 2-16 • AC Loading

Table 2-125 • AC Waveforms, Measuring Points, and Capacitive Loads

Input Low (V)	Input High (V)	Measuring Point* (V)	VREF (typ.) (V)	V_{TT} (typ.) (V)	C_{LOAD} (pF)
VREF - 0.05	VREF + 0.05	0.8	0.8	1.2	10

Note: *Measuring point = V_{trip} . See Table 2-29 on page 2-25 for a complete table of trip points.

Timing Characteristics

Table 2-126 • 2.5 V GTL

Military-Case Conditions: $T_J = 125^\circ\text{C}$, Worst-Case $V_{CC} = 1.14 \text{ V}$,
Worst-Case $V_{CCI} = 3.0 \text{ V}$, $V_{REF} = 0.8 \text{ V}$
Applicable to Pro I/Os for A3PE600L and A3PE3000L Only

Speed Grade	t_{DOUT}	t_{DP}	t_{DIN}	t_{PY}	t_{EOUT}	t_{ZL}	t_{ZH}	t_{LZ}	t_{HZ}	t_{ZLS}	t_{ZHS}	Units
Std.	0.80	2.11	0.05	2.26	0.52	2.14	2.11	-	-	4.34	4.31	ns
-1	0.68	1.79	0.05	1.93	0.44	1.82	1.79	-	-	3.70	3.68	ns

Note: For specific junction temperature and voltage supply levels, refer to Table 2-6 on page 2-6 for derating values.

Table 2-127 • 2.5 V GTL

Military-Case Conditions: $T_J = 125^\circ\text{C}$, $V_{CC} = 1.425 \text{ V}$,
Worst-Case $V_{CCI} = 3.0 \text{ V}$, $V_{REF} = 0.8 \text{ V}$
Applicable to Pro I/Os for A3PE600L and A3PE3000L Only

Speed Grade	t_{DOUT}	t_{DP}	t_{DIN}	t_{PY}	t_{EOUT}	t_{ZL}	t_{ZH}	t_{LZ}	t_{HZ}	t_{ZLS}	t_{ZHS}	Units
Std.	0.61	2.02	0.04	2.04	0.40	1.98	2.02	-	-	3.45	3.49	ns
-1	0.52	1.72	0.03	1.73	0.34	1.69	1.72	-	-	2.93	2.97	ns

Note: For specific junction temperature and voltage supply levels, refer to Table 2-6 on page 2-6 for derating values.

3.3 V GTL+

Gunning Transceiver Logic Plus is a high-speed bus standard (JESD8-3). It provides a differential amplifier input buffer and an open-drain output buffer. The VCCI pin should be connected to 3.3 V.

Table 2-128 • Minimum and Maximum DC Input and Output Levels

3.3 V GTL+	VIL		VIH		VOL	VOH	IOL	IOH	IOSL	IOSH	IIL ¹	IIH ²
Drive Strength	Min. V	Max. V	Min. V	Max. V	Max. V	Min. V	mA	mA	Max. mA ³	Max. mA ³	μA ⁴	μA ⁴
35 mA	-0.3	VREF - 0.1	VREF + 0.1	3.6	0.6	-	35	35	268	181	15	15

Notes:

1. I_{IL} is the input leakage current per I/O pin over recommended operating conditions where $-0.3\text{ V} < V_{IN} < V_{IL}$.
2. I_{IH} is the input leakage current per I/O pin over recommended operating conditions $V_{IH} < V_{IN} < V_{CCI}$. Input current is larger when operating outside recommended ranges.
3. Currents are measured at 100°C junction temperature and maximum voltage.
4. Currents are measured at 125°C junction temperature.

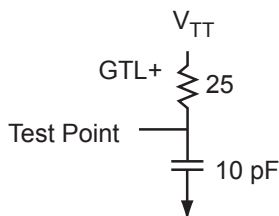


Figure 2-17 • AC Loading

Table 2-129 • AC Waveforms, Measuring Points, and Capacitive Loads

Input Low (V)	Input High (V)	Measuring Point* (V)	VREF (typ.) (V)	VTT (typ.) (V)	C _{LOAD} (pF)
VREF - 0.1	VREF + 0.1	1.0	1.0	1.5	10

Note: *Measuring point = V_{trip} . See Table 2-29 on page 2-25 for a complete table of trip points.

Timing Characteristics

Table 2-130 • 3.3 V GTL+

Military-Case Conditions: $T_J = 125^\circ\text{C}$, Worst-Case VCC = 1.14 V,
Worst-Case VCCI = 3.0 V, VREF = 1.0 V
Applicable to Pro I/Os for A3PE600L and A3PE3000L Only

Speed Grade	t _{DOUT}	t _{DP}	t _{DIN}	t _{PY}	t _{EOUT}	t _{ZL}	t _{ZH}	t _{LZ}	t _{HZ}	t _{ZLS}	t _{ZHS}	Units
Std.	0.80	2.04	0.05	2.34	0.52	2.07	2.03	-	-	4.28	4.24	ns
-1	0.68	1.74	0.05	1.99	0.44	1.76	1.73	-	-	3.64	3.61	ns

Note: For specific junction temperature and voltage supply levels, refer to Table 2-6 on page 2-6 for derating values.

Table 2-131 • 3.3 V GTL+

Military-Case Conditions: $T_J = 125^\circ\text{C}$, VCC = 1.425 V,
Worst-Case VCCI = 3.0 V, VREF = 1.0 V
Applicable to Pro I/Os for A3PE600L and A3PE3000L Only

Speed Grade	t _{DOUT}	t _{DP}	t _{DIN}	t _{PY}	t _{EOUT}	t _{ZL}	t _{ZH}	t _{LZ}	t _{HZ}	t _{ZLS}	t _{ZHS}	Units
Std.	0.61	1.95	0.04	2.11	0.40	1.92	1.95	-	-	3.38	3.41	ns
-1	0.52	1.66	0.03	1.79	0.34	1.63	1.66	-	-	2.88	2.90	ns

Note: For specific junction temperature and voltage supply levels, refer to Table 2-6 on page 2-6 for derating values.

LVPECL

Low-Voltage Positive Emitter-Coupled Logic (LVPECL) is another differential I/O standard. It requires that one data bit be carried through two signal lines. Like LVDS, two pins are needed. It also requires external resistor termination.

The full implementation of the LVDS transmitter and receiver is shown in an example in [Figure 2-27](#). The building blocks of the LVPECL transmitter-receiver are one transmitter macro, one receiver macro, three board resistors at the transmitter end, and one resistor at the receiver end. The values for the three driver resistors are different from those used in the LVDS implementation because the output standard specifications are different.

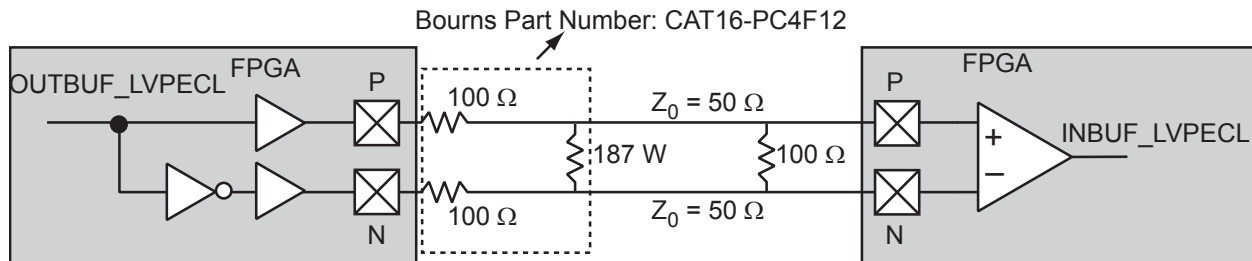


Figure 2-27 • LVPECL Circuit Diagram and Board-Level Implementation

Table 2-165 • Minimum and Maximum DC Input and Output Levels

DC Parameter	Description	Min.	Max.	Min.	Max.	Min.	Max.	Units
VCCI	Supply Voltage	3.0		3.3		3.6		V
VOL	Output Low Voltage	0.96	1.27	1.06	1.43	1.30	1.57	V
VOH	Output High Voltage	1.8	2.11	1.92	2.28	2.13	2.41	V
VIL, VIH	Input Low, Input High Voltages	0	3.3	0	3.6	0	3.9	V
VODIFF	Differential Output Voltage	0.625	0.97	0.625	0.97	0.625	0.97	V
VOCM	Output Common-Mode Voltage	1.762	1.98	1.762	1.98	1.762	1.98	V
VICM	Input Common-Mode Voltage	1.01	2.57	1.01	2.57	1.01	2.57	V
VIDIFF	Input Differential Voltage	300		300		300		mV

Table 2-166 • AC Waveforms, Measuring Points, and Capacitive Loads

Input Low (V)	Input High (V)	Measuring Point* (V)
1.64	1.94	Cross point

Note: *Measuring point = V_{trip} . See [Table 2-29](#) on page 2-25 for a complete table of trip points.

Output Register

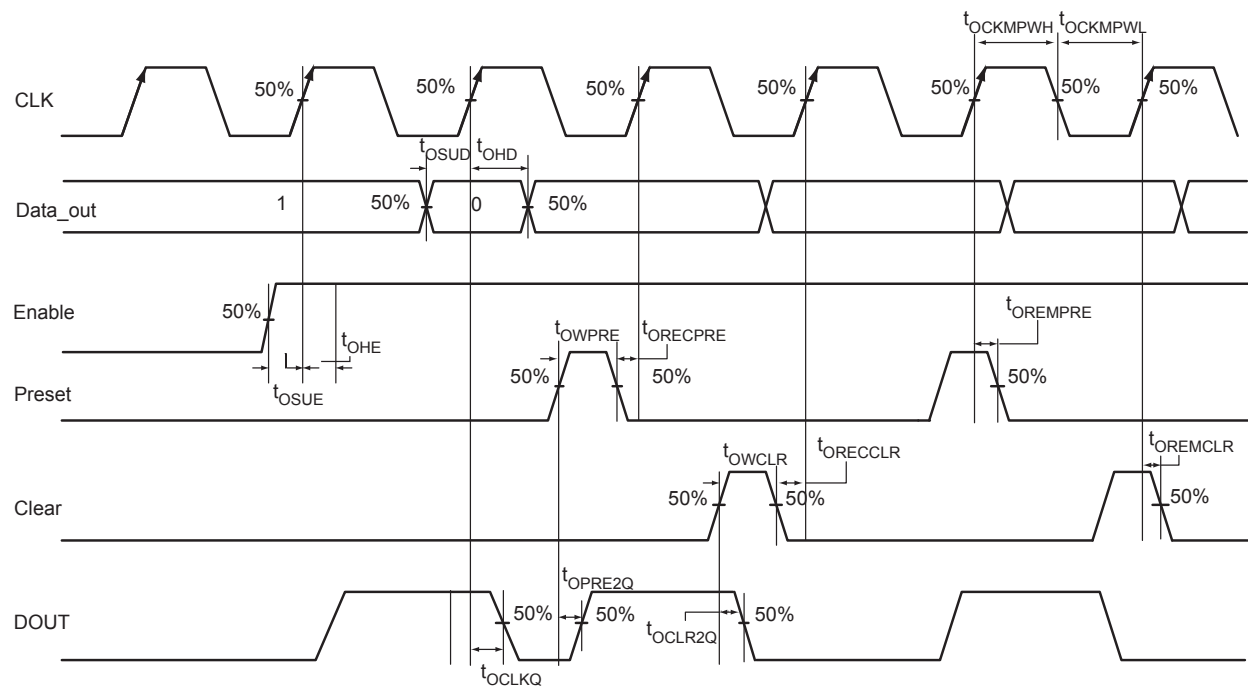


Figure 2-31 • Output Register Timing Diagram

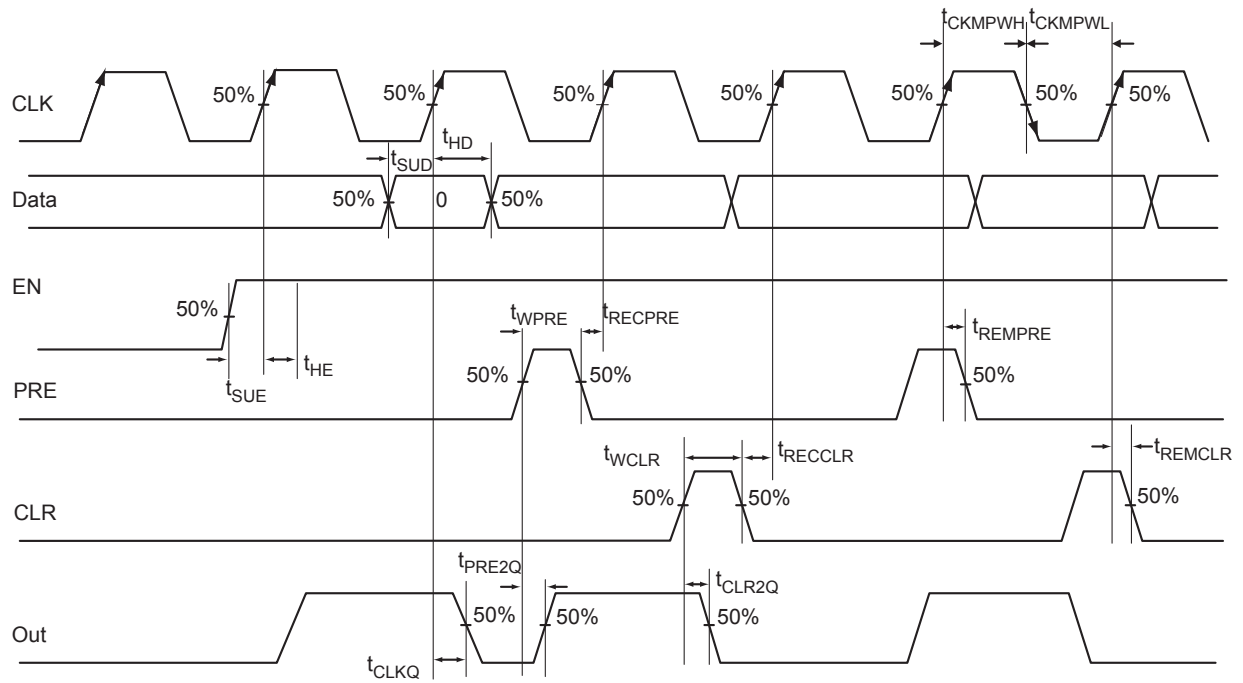


Figure 2-40 • Timing Model and Waveforms

Global Resource Characteristics

A3P1000 Clock Tree Topology

Clock delays are device-specific. [Figure 2-41](#) is an example of a global tree used for clock routing. The global tree presented in [Figure 2-41](#) is driven by a CCC located on the west side of the A3P1000 device. It is used to drive all D-flip-flops in the device.

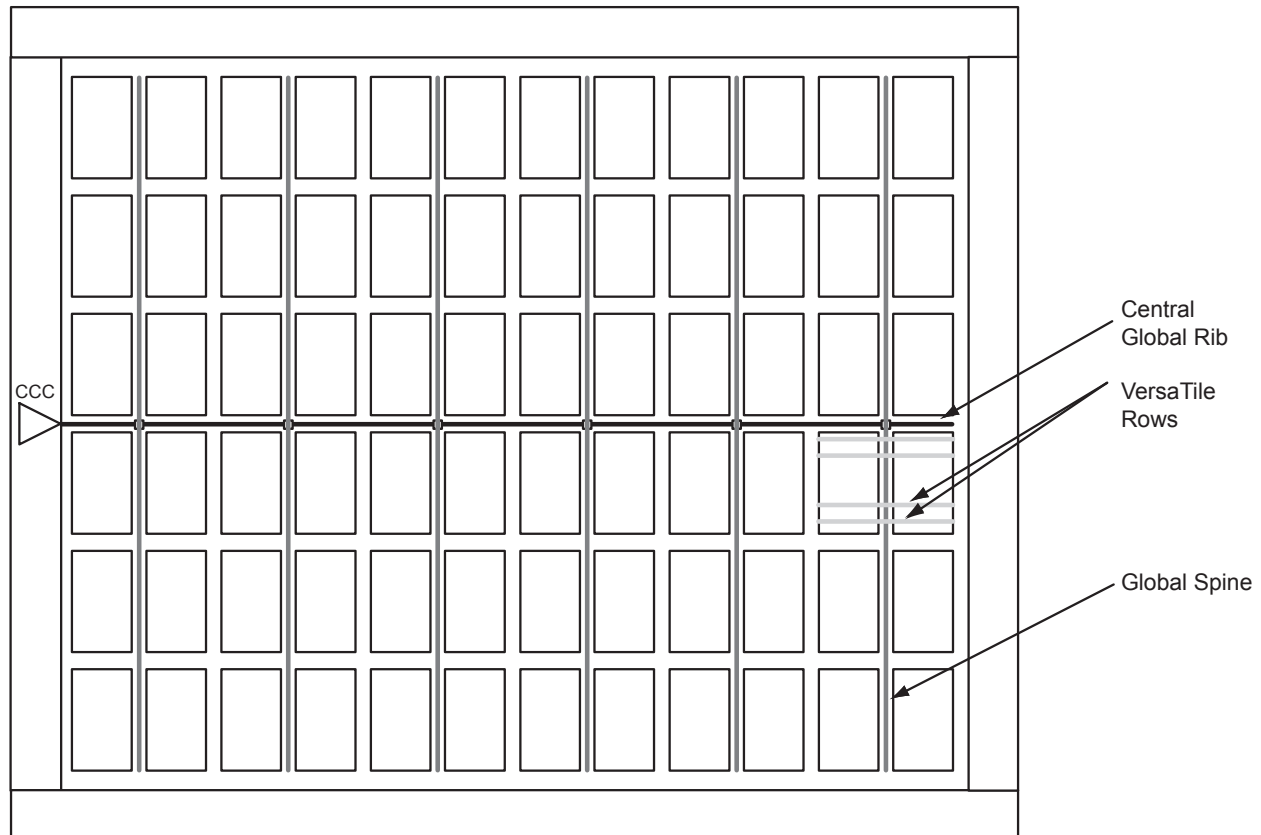


Figure 2-41 • Example of Global Tree Use in an A3P1000 Device for Clock Routing

Table 2-199 • A3P250 Global Resource
Military-Case Conditions: $T_J = 125^{\circ}\text{C}$, $V_{CC} = 1.425\text{ V}$

Parameter	Description	–1		Std.		Units
		Min. ¹	Max. ²	Min. ¹	Max. ²	
t_{RCKL}	Input Low Delay for Global Clock	0.97	1.24	1.14	1.46	ns
t_{RCKH}	Input High Delay for Global Clock	0.94	1.27	1.11	1.49	ns
$t_{RCKMPWH}$	Minimum Pulse Width High for Global Clock					ns
$t_{RCKMPWL}$	Minimum Pulse Width Low for Global Clock					ns
t_{RCKSW}	Maximum Skew for Global Clock		0.32		0.38	ns
F_{RMAX}	Maximum Frequency for Global Clock					MHz

Notes:

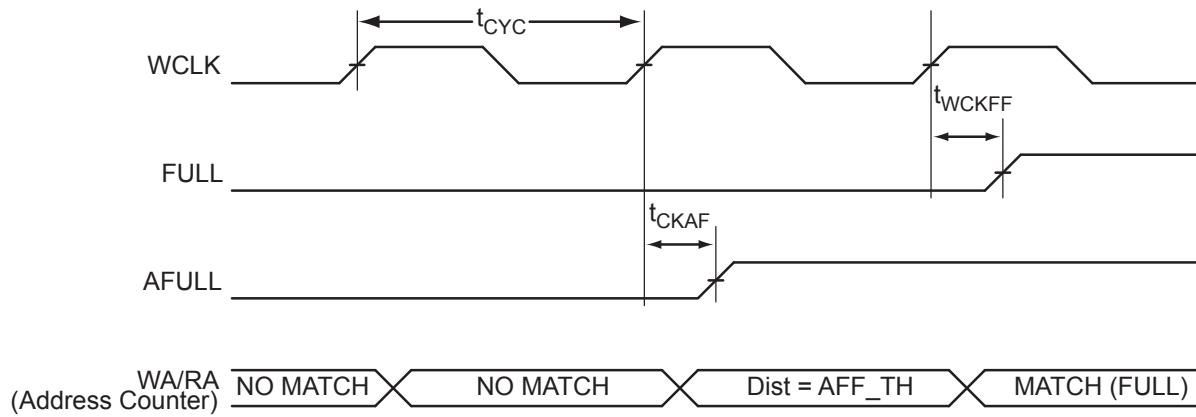
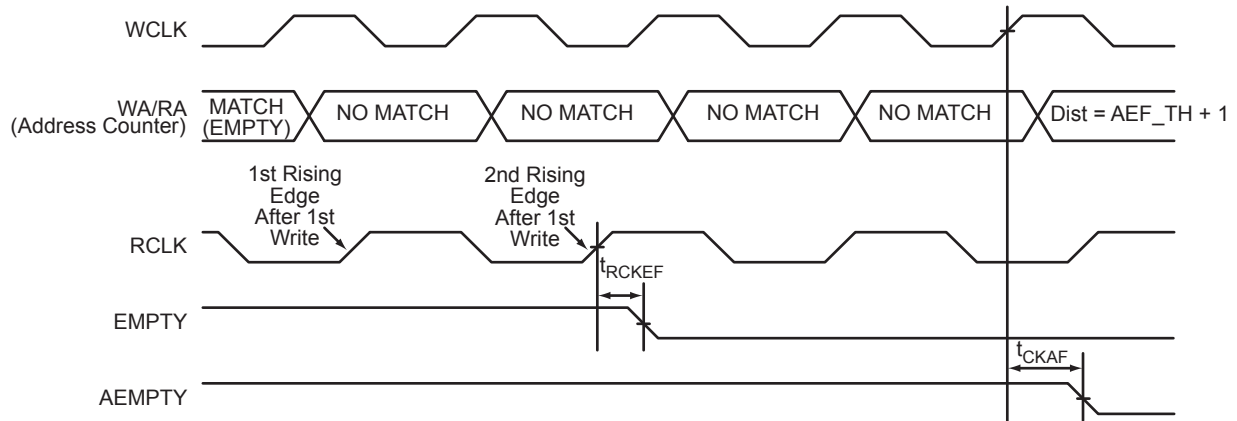
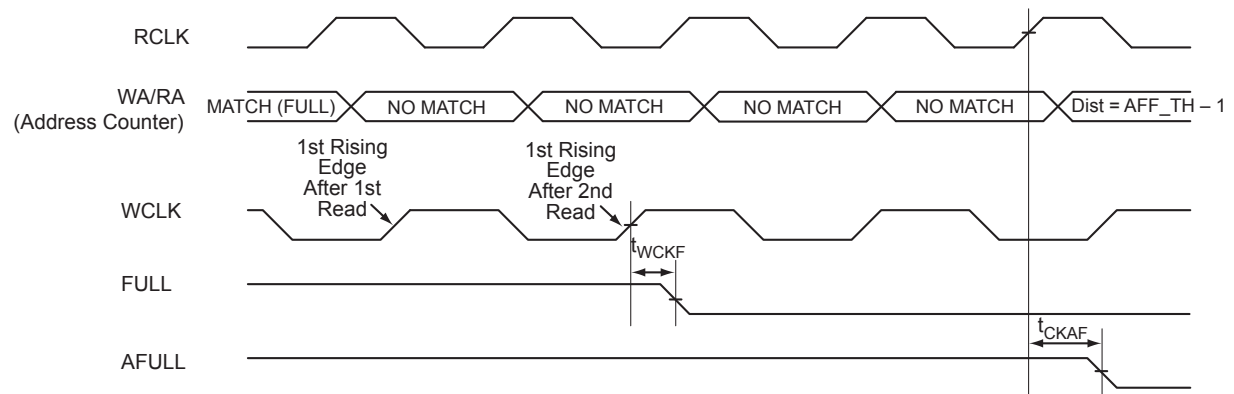
1. Value reflects minimum load. The delay is measured from the CCC output to the clock pin of a sequential element, located in a lightly loaded row (single element is connected to the global net).
2. Value reflects maximum load. The delay is measured on the clock pin of the farthest sequential element, located in a fully loaded row (all available flip-flops are connected to the global net in the row).
3. For specific junction temperature and voltage supply levels, refer to [Table 2-7 on page 2-6](#) for derating values.

Table 2-200 • A3P1000 Global Resource
Military-Case Conditions: $T_J = 125^{\circ}\text{C}$, $V_{CC} = 1.425\text{ V}$

Parameter	Description	–1		Std.		Units
		Min. ¹	Max. ²	Min. ¹	Max. ²	
t_{RCKL}	Input Low Delay for Global Clock	1.18	1.44	1.39	1.70	ns
t_{RCKH}	Input High Delay for Global Clock	1.17	1.48	1.37	1.74	ns
$t_{RCKMPWH}$	Minimum Pulse Width High for Global Clock					ns
$t_{RCKMPWL}$	Minimum Pulse Width Low for Global Clock					ns
t_{RCKSW}	Maximum Skew for Global Clock		0.32		0.37	ns
F_{RMAX}	Maximum Frequency for Global Clock					MHz

Notes:

1. Value reflects minimum load. The delay is measured from the CCC output to the clock pin of a sequential element, located in a lightly loaded row (single element is connected to the global net).
2. Value reflects maximum load. The delay is measured on the clock pin of the farthest sequential element, located in a fully loaded row (all available flip-flops are connected to the global net in the row).
3. For specific junction temperature and voltage supply levels, refer to [Table 2-7 on page 2-6](#) for derating values.


Figure 2-52 • FIFO FULL Flag and AFULL Flag Assertion

Figure 2-53 • FIFO EMPTY Flag and AEMPTY Flag Deassertion

Figure 2-54 • FIFO FULL Flag and AFULL Flag Deassertion

Timing Characteristics

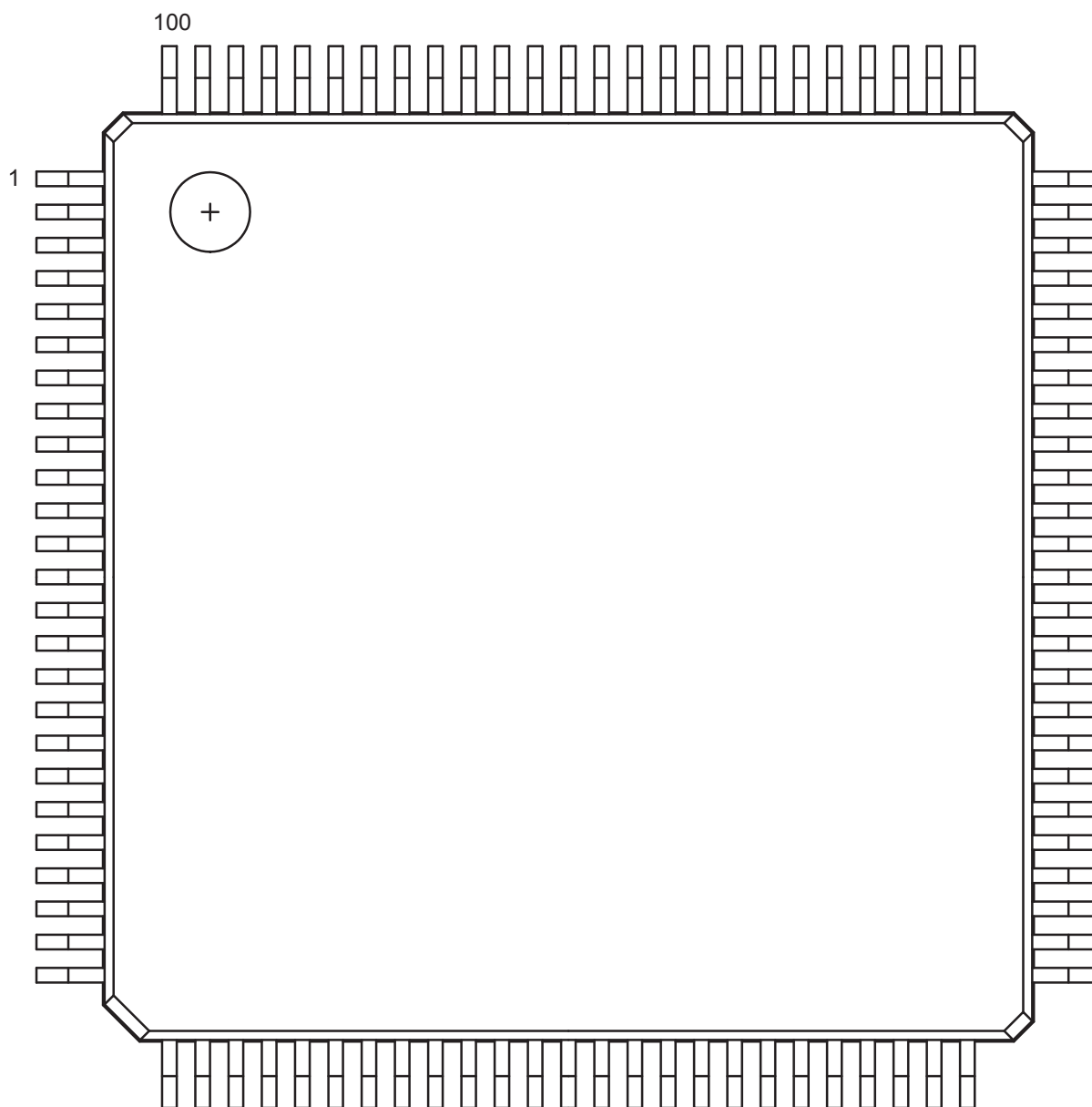
Table 2-209 • FIFO Worst Military-Case Conditions: $T_J = 125^{\circ}\text{C}$, $V_{CC} = 1.14\text{ V}$ for A3PE600L and A3PE3000L

Parameter	Description	–1	Std.	Units
t_{ENS}	REN, WEN Setup Time	1.91	2.24	ns
t_{ENH}	REN, WEN Hold Time	0.03	0.03	ns
t_{BKS}	BLK Setup Time	0.40	0.47	ns
t_{BKH}	BLK Hold Time	0.00	0.00	ns
t_{DS}	Input Data (WD) Setup Time	0.25	0.30	ns
t_{DH}	Input Data (WD) Hold Time	0.00	0.00	ns
t_{CKQ1}	Clock HIGH to New Data Valid on RD (flow-through)	3.26	3.84	ns
t_{CKQ2}	Clock HIGH to New Data Valid on RD (pipelined)	1.24	1.46	ns
t_{RCKEF}	RCLK HIGH to Empty Flag Valid	2.38	2.80	ns
t_{WCKFF}	WCLK HIGH to Full Flag Valid	2.26	2.66	ns
t_{CKAF}	Clock HIGH to Almost Empty/Full Flag Valid	8.57	10.08	ns
t_{RSTFG}	RESET LOW to Empty/Full Flag Valid	2.34	2.76	ns
t_{RSTAF}	RESET LOW to Almost Empty/Full Flag Valid	8.48	9.97	ns
t_{RSTBQ}	RESET LOW to Data Out LOW on RD (flow-through)	1.28	1.50	ns
	RESET LOW to Data Out LOW on RD (pipelined)	1.28	1.50	ns
t_{REMRSTB}	RESET Removal	0.40	0.47	ns
t_{RECRSTB}	RESET Recovery	2.08	2.44	ns
t_{MPWRSTB}	RESET Minimum Pulse Width	0.66	0.76	ns
t_{CYC}	Clock Cycle Time	6.08	6.99	ns
F_{MAX}	Maximum Frequency for FIFO	164	143	MHz

Note: For specific junction temperature and voltage supply levels, refer to [Table 2-6 on page 2-6](#) for derating values.

4 – Package Pin Assignments

VQ100



Note: This is the top view of the package.

Note

For Package Manufacturing and Environmental information, visit the Resource Center at <http://www.microsemi.com/products/fpga-soc/solutions>.

FG484		FG484		FG484	
Pin Number	A3P1000 Function	Pin Number	A3P1000 Function	Pin Number	A3P1000 Function
K13	GND	M4	GFA2/IO206PDB3	N17	IO100NPB1
K14	VCC	M5	GFA1/IO207PDB3	N18	IO102NDB1
K15	VCCIB1	M6	VCCPLF	N19	IO102PDB1
K16	GCC1/IO91PPB1	M7	IO205NDB3	N20	NC
K17	IO90NPB1	M8	GFB2/IO205PDB3	N21	IO101NPB1
K18	IO88PDB1	M9	VCC	N22	IO103PDB1
K19	IO88NDB1	M10	GND	P1	NC
K20	IO94NPB1	M11	GND	P2	IO199PDB3
K21	IO98NDB1	M12	GND	P3	IO199NDB3
K22	IO98PDB1	M13	GND	P4	IO202NDB3
L1	NC	M14	VCC	P5	IO202PDB3
L2	IO200PDB3	M15	GCB2/IO95PPB1	P6	IO196PPB3
L3	IO210NPB3	M16	GCA1/IO93PPB1	P7	IO193PPB3
L4	GFB0/IO208NPB3	M17	GCC2/IO96PPB1	P8	VCCIB3
L5	GFA0/IO207NDB3	M18	IO100PPB1	P9	GND
L6	GFB1/IO208PPB3	M19	GCA2/IO94PPB1	P10	VCC
L7	VCOMPLF	M20	IO101PPB1	P11	VCC
L8	GFC0/IO209NPB3	M21	IO99PPB1	P12	VCC
L9	VCC	M22	NC	P13	VCC
L10	GND	N1	IO201NDB3	P14	GND
L11	GND	N2	IO201PDB3	P15	VCCIB1
L12	GND	N3	NC	P16	GDB0/IO112NPB1
L13	GND	N4	GFC2/IO204PDB3	P17	IO106NDB1
L14	VCC	N5	IO204NDB3	P18	IO106PDB1
L15	GCC0/IO91NPB1	N6	IO203NDB3	P19	IO107PDB1
L16	GCB1/IO92PPB1	N7	IO203PDB3	P20	NC
L17	GCA0/IO93NPB1	N8	VCCIB3	P21	IO104PDB1
L18	IO96NPB1	N9	VCC	P22	IO103NDB1
L19	GCB0/IO92NPB1	N10	GND	R1	NC
L20	IO97PDB1	N11	GND	R2	IO197PPB3
L21	IO97NDB1	N12	GND	R3	VCC
L22	IO99NPB1	N13	GND	R4	IO197NPB3
M1	NC	N14	VCC	R5	IO196NPB3
M2	IO200NDB3	N15	VCCIB1	R6	IO193NPB3
M3	IO206NDB3	N16	IO95NPB1	R7	GEC0/IO190NPB3

FG484		FG484	
Pin Number	A3P1000 Function	Pin Number	A3P1000 Function
Y3	NC	AA16	IO122RSB2
Y4	IO182RSB2	AA17	IO119RSB2
Y5	GND	AA18	IO117RSB2
Y6	IO177RSB2	AA19	NC
Y7	IO174RSB2	AA20	NC
Y8	VCC	AA21	VCCIB1
Y9	VCC	AA22	GND
Y10	IO154RSB2	AB1	GND
Y11	IO148RSB2	AB2	GND
Y12	IO140RSB2	AB3	VCCIB2
Y13	NC	AB4	IO180RSB2
Y14	VCC	AB5	IO176RSB2
Y15	VCC	AB6	IO173RSB2
Y16	NC	AB7	IO167RSB2
Y17	NC	AB8	IO162RSB2
Y18	GND	AB9	IO156RSB2
Y19	NC	AB10	IO150RSB2
Y20	NC	AB11	IO145RSB2
Y21	NC	AB12	IO144RSB2
Y22	VCCIB1	AB13	IO132RSB2
AA1	GND	AB14	IO127RSB2
AA2	VCCIB3	AB15	IO126RSB2
AA3	NC	AB16	IO123RSB2
AA4	IO181RSB2	AB17	IO121RSB2
AA5	IO178RSB2	AB18	IO118RSB2
AA6	IO175RSB2	AB19	NC
AA7	IO169RSB2	AB20	VCCIB2
AA8	IO166RSB2	AB21	GND
AA9	IO160RSB2	AB22	GND
AA10	IO152RSB2		
AA11	IO146RSB2		
AA12	IO139RSB2		
AA13	IO133RSB2		
AA14	NC		
AA15	NC		

FG484		FG484		FG484	
Pin Number	A3PE3000L Function	Pin Number	A3PE3000L Function	Pin Number	A3PE3000L Function
H13	VCCIB1	K4	IO279NDB7V0	L17	GCA0/IO114NPB3V0
H14	VCCIB1	K5	IO283NDB7V1	L18	VCOMPLC
H15	VMV1	K6	IO281NDB7V0	L19	GCB0/IO113NPB2V3
H16	GBC2/IO84PDB2V0	K7	GFC1/IO275PPB7V0	L20	IO110PPB2V3
H17	IO83NDB2V0	K8	VCCIB7	L21	IO111NDB2V3
H18	IO100NDB2V2	K9	VCC	L22	IO111PDB2V3
H19	IO100PDB2V2	K10	GND	M1	GNDQ
H20	VCC	K11	GND	M2	IO255NPB6V2
H21	VMV2	K12	GND	M3	IO272NDB6V4
H22	IO105PDB2V2	K13	GND	M4	GFA2/IO272PDB6V4
J1	IO285NDB7V1	K14	VCC	M5	GFA1/IO273PDB6V4
J2	IO285PDB7V1	K15	VCCIB2	M6	VCCPLF
J3	VMV7	K16	GCC1/IO112PPB2V3	M7	IO271NDB6V4
J4	IO279PDB7V0	K17	IO108NDB2V3	M8	GFB2/IO271PDB6V4
J5	IO283PDB7V1	K18	IO108PDB2V3	M9	VCC
J6	IO281PDB7V0	K19	IO110NPB2V3	M10	GND
J7	IO287NDB7V1	K20	IO106NPB2V3	M11	GND
J8	VCCIB7	K21	IO109NDB2V3	M12	GND
J9	GND	K22	IO107NDB2V3	M13	GND
J10	VCC	L1	IO257PSB6V2	M14	VCC
J11	VCC	L2	IO276PDB7V0	M15	GCB2/IO116PPB3V0
J12	VCC	L3	IO276NDB7V0	M16	GCA1/IO114PPB3V0
J13	VCC	L4	GFB0/IO274NPB7V0	M17	GCC2/IO117PPB3V0
J14	GND	L5	GFA0/IO273NDB6V4	M18	VCCPLC
J15	VCCIB2	L6	GFB1/IO274PPB7V0	M19	GCA2/IO115PDB3V0
J16	IO84NDB2V0	L7	VCOMPLF	M20	IO115NDB3V0
J17	IO104NDB2V2	L8	GFC0/IO275NPB7V0	M21	IO126PDB3V1
J18	IO104PDB2V2	L9	VCC	M22	IO124PSB3V1
J19	IO106PPB2V3	L10	GND	N1	IO255PPB6V2
J20	GNDQ	L11	GND	N2	IO253NDB6V2
J21	IO109PDB2V3	L12	GND	N3	VMV6
J22	IO107PDB2V3	L13	GND	N4	GFC2/IO270PPB6V4
K1	IO277NDB7V0	L14	VCC	N5	IO261PPB6V3
K2	IO277PDB7V0	L15	GCC0/IO112NPB2V3	N6	IO263PDB6V3
K3	GNDQ	L16	GCB1/IO113PPB2V3	N7	IO263NDB6V3

FG896	
Pin Number	A3PE3000L Function
H26	IO84NDB2V0
H27	IO96PDB2V1
H28	IO96NDB2V1
H29	IO89PDB2V0
H30	IO89NDB2V0
J1	IO290NDB7V2
J2	IO290PDB7V2
J3	IO302NDB7V3
J4	IO302PDB7V3
J5	IO295NDB7V2
J6	IO299NDB7V3
J7	VCCIB7
J8	VCCPLA
J9	VCC
J10	IO04NPB0V0
J11	IO18NDB0V2
J12	IO20NDB0V2
J13	IO20PDB0V2
J14	IO32NDB0V3
J15	IO32PDB0V3
J16	IO42PDB1V0
J17	IO44NDB1V0
J18	IO44PDB1V0
J19	IO54NDB1V1
J20	IO54PDB1V1
J21	IO76NPB1V4
J22	VCC
J23	VCCPLB
J24	VCCIB2
J25	IO90PDB2V1
J26	IO90NDB2V1
J27	GBB2/IO83PDB2V0
J28	IO83NDB2V0
J29	IO91PDB2V1
J30	IO91NDB2V1
K1	IO288NDB7V1

Revision	Changes	Page
Revision 1 (June 2011)	In the " High Performance " section, 66-Bit PCI was corrected to 64-Bit PCI (SAR 31977).	I
	The A3P250 device and VQ100 package were added to product tables in the " Military ProASIC3/EL Low Power Flash FPGAs " chapter (SAR 30526).	I
	The Y security option and Licensed DPA Logo were added to the " Military ProASIC3/EL Ordering Information " section. The trademarked Licensed DPA Logo identifies that a product is covered by a DPA counter-measures license from Cryptography Research (SAR 32151).	III
	The A3P250 device was added to applicable tables in the " Military ProASIC3/EL DC and Switching Characteristics " chapter (SAR 30526).	2-1
	The VPUMP voltage for operation mode was changed from "0 to 3.45 V" to "0 to 3.6 V" in Table 2-2 • Recommended Operating Conditions ¹ (SAR 25220).	2-2
	3.3 V LVCMOS wide range and 1.2 V LVCMOS wide range were added to applicable tables in the following sections (SAR 28061):	
	Table 2-2 • Recommended Operating Conditions ¹ "Power per I/O Pin" "Overview of I/O Performance" "Summary of I/O Timing Characteristics – Default I/O Software Settings" "User I/O Characteristics" "Detailed I/O DC Characteristics" "Single-Ended I/O Characteristics" (SAR 31925)	2-2 2-9 2-22 2-25 2-18 2-29 2-37